Filename: PMP6672_RevB_BOM.XLS

Date: 11/15/2011

PMP6672_REVB BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	1nF	Capacitor, Ceramic, 100V, X7R, 10%	0805	Std	Std
1	C100	330pF	Capacitor, Ceramic, 100V, X7R, 10%	0603	Std	Std
2	C10, C11	1uF	Capacitor, Ceramic, 1uF, 100V, X7R, 15%	1210	Std	Std
1	C14	10nF	Capacitor, Ceramic, 100V, X7R, 10%	0603	Std	Std
3	C15, C16, C17	47uF	Capacitor, Ceramic, 10V, X5R, 15%	1210	Std	Std
2	C18, C19	330uF	Capacitor, Aluminum, 6.3V, 20%	0.260 x 0.276 inch	EEVFK0J331XP	Panasonic
1	C2	0.1uF	Capacitor, Ceramic, 100V, X7R, 10%	0805	Std	Std
1	C20	1uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	Std	Std
2	C21, C32	1.0uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
1	C22	1200pF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
1	C23	1000pF	Capacitor, Ceramic, 100V, X7R, 15%	0603	Std	Std
1	C24	2200pF	Capacitor, Ceramic, 2KV, X7R, 15%	1812	Std	Std
1	C25	1.0uF	Capacitor, Ceramic, 25V, X7R, 10%	0805	Std	Std
1	C26	22uF	Capacitor, Aluminum, 25V, 20%	5x5.8mm	EEVFK1E220R	Panasonic
2	C27, C28	0.47uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	Std	Std
1	C29	3300pF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
4	C3, C4, C5, C6	0.01uF	Capacitor, Ceramic, 100V, X7R, 15%	0603	Std	Std
1	C30	27nF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
1	C31	6.8nF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
1	C7	1000pF	Capacitor, Ceramic, 2kV, X7R, 15%	1210	Std	Std
3	C8, C12, C13	0.1uF	Capacitor, Ceramic, 100V, X7R, 15%	0805	Std	Std
1	C9	47uF	Capacitor, Aluminum, 63V, ±20%	0.328 x 0.390 inch	EEVFK1J470P	Panasonic
1	CL1	NA	Current Loop, 0.025 holes	0.120 X 0.075 inch	NA	NA
1	D1	B2100	Diode, Schottky, 2-A, 100-V	SMB	B2100-13	Diodes Inc
1	D100	1N4148W-7-F	Diode, Signal, 300-mA, 75-V, 350-mW	SOD-123	1N4148W-7-F	Diodes
2	D14, D18	SMAJ58A	Diode, TVS, 58-V, 1W	SMA	SMAJ58A	Diodes Inc.
1	D15	MURS120T3	Diode, UltraFast Rectifier, 1-A, 200-V	SMB	MURS120T3	On Semi
1	D16	BAV20WS	Diode, Small Signal, 250mA, 150V	SOD-323	BAV20WS	Micro Commercial Components
2	D17, D19	BAV99	Diode, Dual Ultra Fast, Series, 200-mA, 70-V	SOT23	BAV99	Fairchild
2	D2, D3	LN1371G	Diode, LED, Green, 10-mA, 2.6-mcd	0.114 X 0.049 inch	LN1371G	Panasonic
1	D4	LN1271RAL	Diode, LED, Ultra Bright Red, 10-mA, 5-mcd	0.114 X 0.049 inch	LN1271RAL	Panasonic
9	D5, D6, D7, D8, D9, D10, D11, D12, D13	B1100	Diode, Schottky, 1A, 100V	SMA	B1100	Diodes, Inc
4	FB1, FB2, FB3, FB4	500	Bead, Ferrite, 2000mA, 60m-ohm	1206	MI1206L501R-10	Steward
2	J1, J2	5520252-4	Connector, Jack, Modular, Rt. Angle,8 POS	0.705 x 0.820 inch	5520252-4	AMP
2	J3, J11	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	
2	J4, J10	PTC36SAAN	Header, Male 3-pin, 100mil spacing, (36-pin strip)	0.100 inch x 3	PTC36SAAN	Sullins
5	J5, J6, J7, J8, J9	PTC36SAAN	Header, Male 2-pin, 100mil spacing, (36-pin strip)	0.100 inch x 2	PTC36SAAN	Sullins
1	L1	3.3uH	Inductor, SMT, 2.0A, 80-milliohm	4.45x6.6mm	DO1608C-332	Coilcraft

1	L2	0.33uH	Inductor, SMT, 6.26A, 7.4-milliohm	0.300 sq"	DR74-R33	Cooper
1	Q1	SiR422DP	MOSFET, NChan, 40V, 50A, 2.8 millohm	PWRPAK S0-8	SiR422DP	Vishay-Siliconix
1	Q2	Si7898DP or FDMS2572	MOSFET, NChannel, 150V, 4.8A, 85-millohm	PWRPAK S0-8 or POWER 56	Si7898DP or FDMS2572	Vishay or Fairchild
1	Q3	MMBT3906	Bipolar, PNP, 40V, 200mA, 225mW	SOT23	MMBT3906LT1	On Semi
1	R1	100K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R100	121K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R12	39K	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Std	Std
1	R13	24.9k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R14, R15	69.8K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R16	10	Resistor, Chip, 1/10W, 1%	0805	Std	Std
1	R17	22.1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R18	10	Resistor, Chip, 1/16W, 5%	0603	Std	Std
1	R19	63.4	Resistor, Chip, 1/10W, 1%	0805	Std	Std
1	R2	15K	Resistor, Chip, 1/4W, 1%	1210	Std	Std
1	R20	4.7	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R21	332	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R22	0.18	Resistor, Chip, 1/2W, 1%	2010	Std	Std
2	R23, R28	10K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R24	1.5K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R25	2K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R26	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R27	604	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R29	41.2K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R3, R4	1K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R30	13.7K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R5	6.49K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R6	4.02K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R7	8.87K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
4	R8, R9, R10, R11	75	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	T1	ETH1-230LD	XFMR, Mid-Power PoE Magnetics	S0 14 Wide	ETH1-230LD	Coilcraft
1	T2	JA4456-DL	Transformer, SMT For PoE/PD, 25W, 2.8A	0.810 x 1.181 inch	JA4456-DL	Coilcraft
1	T3	PA0184	XFMR, SMT Gate Drive	0.355 X 0.340 inch	PA0184	Pulse
5	TP1, TP6, TP7, TP9, TP17	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
3	TP10, TP13, TP18	5013	Test Point, Orange, Thru Hole	0.125 x 0.125 inch	5013	Keystone
7	TP2, TP3, TP4, TP5, TP11, TP16, TP19	5012	Test Point, White, Thru Hole	0.125 x 0.125 inch	5012	Keystone
4	TP8, TP12, TP14, TP15	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone
1	U1	FOD817D	IC, Optocoupler, 70-V, 300 - 600% CTR	SMT-4PDIP	FOD817DS	Fairchild
1	U2	TPS23754PWP	IC, IEEE 802.3at PoE Interface and Isolated Converter Controller	PWP20	TPS23754PWP	TI
1	U3	TCMT1107	IC, Photocoupler, 3750VRMS, 80-160% CTR	MF4	TCMT1107	Vishay
1	U4	TLV431A	IC, Shunt Regulator, 6V, 10mA, 1%	SOT23-5	TLV431ACDBVR	TI
6	--		Shunt, Black	100-mil	929950-00	3M
4		2566	Rubber Bumbers		2566	

1	--		PCB, 5.90 In x 2.03 In x 0.062 In		HPA420	Any
Notes:	1. These assemblies are ESD sensitive, ESD precautions shall be observed.					
	2. These assemblies must be clean and free from flux and all contaminants.					
	Use of no clean flux is not acceptable.					
	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.					
	4. Ref designators marked with an asterisk ('**') cannot be substituted.					
	All other components can be substituted with equivalent MFG's components.					
	5. Install Wire, 24 AWG, Solid, non-insulated, .30 inches at CL1.					
	6. Place shunts between pins 1 and 2 of J4-J7, J9 and J10					
	7. Add 4 rubber bumpon on each conner of the back side					

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